Application for Scholarship Bond Deferment or Transfer

**Scholarship** Check 🗹 the box (as appropriate)

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| 🗹 NUS Science & Technology Undergraduate Scholarship | 🞏 Sembcorp Undergraduate Scholarship |
| 🞏 SIA-NOL Undergraduate Scholarship | 🞏 Undergraduate Scholarship for PRC Students |

**Bridging Period** Check 🗹 the box (as appropriate)

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| --- | --- | --- | --- | --- |
| 🞏 NA | 🞏 20 Months | 🗹 12 Months | 🞏 7 Months |  |

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| **Name:\_\_\_\_\_\_\_Xiang Shang\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_ Matric/Student No.\_\_\_\_\_G1321002R\_\_\_\_\_\_\_\_\_** |
| Dear scholar,  Upon graduation, you are required to serve your bond in a Singapore entity immediately. To defer your bond for postgraduate studies, overseas work, overseas training or other reasons, or transfer your bond to a Singapore organisation that awarded you a bonded scholarship or training award, you need to fill in this application form **at least 3 months in advance**.  Before you apply, please find out the amount of Banker’s Guarantee (BG) required for bond deferment.  Please proceed to apply for **deferment of tuition grant bond** at https://tgonline.moe.gov.sg **after** you have obtained approval for the deferment of your scholarship bond.  Please fill in the application form by **typing**, and attach the following supporting documents: |

1. **Bond Deferment for Postgraduate Studies**

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| Supporting Documents | | Check 🗹 the box (as appropriate) |
|  | Colour copy of passport and one of the following: (a) NRIC, (b) Student Pass or (c) Work Pass | 🗹 |
|  | Letter of admission for postgraduate course | 🗹 |
|  | Letter of offer of bonded postgraduate scholarship from a Singapore organisation (if any) | 🞏 |
|  | All current and past employment records (if any) | 🗹 |

1. **Bond Deferment for Overseas Work or Training**

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| Supporting Documents | | Check 🗹 the box (as appropriate) |
|  | Colour copy of passport and one of the following: (a) NRIC, (b) Student Pass or (c) Work Pass | 🞏 |
|  | Letter of offer of overseas work or training | 🞏 |
|  | Letter from HR or company director to show either (if any):   1. Employer is a Singapore-based company\* and (1) reasons for posting, (2) start and end date of posting, (3) country posted to, (4) its relationship with the overseas office and (5) percentage of ownership of the overseas office is more than 50%; or 2. HR letter to show that payroll and tax status remains unchanged, i.e. scholar continues to be tax liable in Singapore | 🞏 |
|  | All current and past employment records (if any) | 🞏 |

\*with global or regional HQ in Singapore

1. **Bond Transfer**

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| Supporting Documents | | | | | | | | | | Check 🗹 the box (as appropriate) | | |
|  | Colour copy of passport and one of the following: (a) NRIC, (b) Student Pass or (c) Work Pass | | | | | | | | | 🞏 | | |
|  | Letter of offer of bonded scholarship or training award | | | | | | | | | 🞏 | | |
|  | All current and past employment records (if any) | | | | | | | | | 🞏 | | |
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| 1. **Particulars of Applicant** | | | | | | | | | | | | | |
| Name as in NRIC/Passport (include name in Chinese characters, if applicable)  Xiang Shang  向尚 | | | | | | | | | | | | | |
| FIN/NRIC  S9677458C | | | | Matriculation No.  A0133890A | | Admission Year  2014 | | | Graduation Year  2018 | | | | |
| Name of Course/Title of Degree (if graduated)  Bachelor of Science with Honours (Merit) in Applied Mathematics | | | | | | | | | | | | | |
| Contact Address (Singapore)  461 Clementi Avenue 3 #23-612  Singapore, 120461 | | | | | | Contact Address in Home Country  (state in Chinese characters, if applicable)  Wuhan Rongqiaojinjiang 8-1-4102, China Hubei 430034.  湖北省武汉市硚口区融侨锦江 8-1-4102, 430034 | | | | | | | |
| Contact No. (Singapore)  +65 90371449 | | | | | | Contact No. (Home Country)  +86 13871238696 | | | | | | | |
| Email Address(es)  Xiangshang4@gmail.com | | | | | | | | | | | | | |
| 1. **Employment History After Graduation (attach employment records, if any)** | | | | | | | | | | | | | |
| Start Date  (Month/Year) | | End Date  (Month/Year) | | Name of Employer | | | | | | | Country of Employment | | |
| Jan/2019 | | July/2021 | | Mizuho Bank ltd. | | | | | | | Singapore | | |
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| 1. **Previously Approved Bond Deferment (if any)** | | | | | | | | | | | | | |
| First Deferment   * Postgraduate Studies * Overseas Work or Training * Others (please specify) | | | | | | Second Deferment   * Postgraduate Studies * Overseas Work or Training * Others (please specify) | | | | | | | |
| Start Date of 1st deferment | | | | End Date of 1st deferment | | Start Date of 2nd deferment | | | End Date of 2nd deferment | | | | |
| 1. **Application** | | | | | | | | | | | | | |
| I am applying for   * Bond Deferment for Postgraduate Studies (go to part 4a) * Bond Deferment for Overseas Work or Training (go to part 4b) * Bond Deferment for Other Reasons (go to part 4c) * Bond Transfer (go to part 4d) | | | | | | | | | | | | | |
| * 1. **Bond Deferment for Postgraduate Studies** | | | | | | | | | | | | | |
| Name of Institution  University of California, Los Angeles | | | | Country of Institution  United States | | Faculty/School  Anderson Management school | Course (indicate if Masters/PhD)  Master in Financial Engineering | | | | | | |
| Start Date  Sept 13th 2021 | | | | End Date  Dec 09 2022 | | Offer of bonded scholarship 🞏 Nil 🞏 A\*STAR  🞏 Others(please specify) | | | | | | | |
| Date leaving Singapore (applicable if doing postgraduate studies overseas)  Sept 10th 2021 | | | | | | | | | | | | | |
| Plans after completion of postgraduate studies  After my postgraduate studies, I will:   * Do postdoctoral work in Singapore to serve my bond * Do other work in Singapore to serve my bond * Others (please specify) | | | | | | | | | | | |
| * 1. **Bond Deferment for Overseas Work or Training** | | | | | | | | | | | |
| I am applying for 🞏 Overseas Work 🞏 Overseas Training | | | | | | | | | | | |
| Name of Employer | | | Country of Work or Training | | Address of Work or Training | | | | | | |
| Start Date | | | | | End Date | | | | | | |
| Date leaving Singapore | | | | | | | | | | | |
| Plans after overseas work or training (please specify) | | | | | | | | | | | |
| * 1. **Bond Deferment for Other Reasons** | | | | | | | | | | | |
| Reason for Deferment (please specify and attach all supporting documents) | | | | | | | | | | | |
| Address during Deferment (i.e. where you will be) | | | | | | | | | | | |
| Start Date | | | | | End Date | | | | | | |
| Plans after bond deferment (please specify) | | | | | | | | | | | |
| * 1. **Bond Transfer** | | | | | | | | | | | |
| I am applying to transfer my bond to a Singapore organisation that awarded me a  🞏 bonded scholarship 🞏 training award | | | | | | | | | | | |
| Name of Singapore organisation   * A\*STAR * Others (please specify) | | | | | Name of bonded scholarship or training award | | | | | | |
| Name of Officer in Charge | | | | | Start Date of course | | | End Date of course | | | |
| Contact Number of Officer in Charge | | | | | Email Address of Officer in Charge | | | | | | |
| 1. **Updated Particulars of Existing Sureties for Undergraduate Scholarship Agreement** | | | | | | | | | | | |
| Name of Surety 1  Qu Zhihua | | | | | Name of Surety 2  Xiang Keqin | | | | | | |
| Surety 1’s Home Address  (include address in Chinese characters, if applicable)  Wuhan Rongqiaojinjiang 8-1-4102, China Hubei 430034.  湖北省武汉市硚口区融侨锦江 8-1-4102, 430034 | | | | | Surety 2’s Home Address  (include address in Chinese characters, if applicable)  Wuhan Caidian Qiannianmeili BLK9-2-301,430100  湖北省武汉市千年美丽 9-2-301, 430100 | | | | | | |
| Surety 1’s Contact No.  +86 13607167372 | | | | | Surety 2’s Contact No.  +8613886026386 | | | | | | |
| Surety 1’s Email Address  1991894558@qq.com | | | | | Surety 2’s Email Address  xiangkejian@dpca.com.cn | | | | | | |
| 1. **Any Other Information** | | | | | | | | | | | |
| Any other relevant information that should be considered by the Sponsor in your application | | | | | | | | | | | |
| 1. **Declaration and Consent** | | | | | | | | | | | |
| 1. For applications under part 4a to 4c, should my bond deferment be approved, I agree and undertake to place a Banker’s Guarantee in full within 1 month from the approval date of bond deferment and sign a Supplemental Agreement before the start of my bond deferment. 2. I declare that I have notified my sureties of this application. 3. I declare that all particulars, information and documents given in this application are true and correct to the best of my knowledge and belief, and that I have not wilfully suppressed any material fact. If any of the information given by me in this application is in any way false or incorrect, my application may be rejected, my scholarship may be terminated and I shall be liable to pay liquidated damages. 4. I consent to the collection, use and disclosure of this information according to the Personal Data Protection Act. | | | | | | | | | | | |
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| **Signature of Applicant** | | | | | **Date** | | | | | | |